

L Number	Hits	Search Text	DB	Time stamp
1	24233	(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5	USPAT	2002/08/30 16:33
2	1205	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) with excess	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/30 16:32
9	0	((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) with excess) and ((polish\$3 or CMP) with (BARLi or (i adj line)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/30 16:35
16	102	((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) with excess) and ((polish\$3 or CMP) with (photoresist or polymer or (low adj k)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/30 16:39
23	28	(((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) with excess) and ((polish\$3 or CMP) with (photoresist or polymer or (low adj k)))) and (excess with (photoresist or polymer or (low adj k)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/30 16:40